Tool ID: 210 Tool Location: 110

Equipment Information Sheet

Primaxx Vapor HF Etcher

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email. 607-254-4813 Mac McMurdy Manager: Backup: Phil Infante 607-254-4926

SAFETY

- The system uses anyhdrous HF gas for etching.
- Nitrile gloves only (thin)
- Do not touch interior of chamber with gloves. Use plastic piece to push and pull wafer holder from chamber.
- · No doped oxides

USAGE RESTRICTIONS

Users must not logout of coral until the system finishes 3 pump/purge cycles and gets to the "waiting to vent" state.

SCHEDULING/SIGN-UP RESTRICTIONS

None

Minimum Tool Time: 15

minutes

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds	
Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No resist allowed in tool.
- No doped oxides (PSG, BPSG) allowed.
- Use aluminum carrier plate for pieces.

Last Updated: 03/24/2021